



Device = VS1033D/LSR  
 Package = LQFP 48L 7x7x1.4  
 REF DOC = BF 51303 REV B

Document: A  
 Rev: 2.1  
 Marking on device:

**VS1033D**  
**PPPPPPPPPP**  
**YYWW**

where, P P P P P P P P P P = Lot ID  
 Y Y W W = assembly Year and Week > 0932

no	Part Name	Material Name	Component WT (mg)	Material Content (Element)	CAS#	Element Wt (%)	Element WT (mg)	WT% of total unit Wt	ppm
1	Die	Silicon Chip	15.957	Silicon	7440-21-3	100.00	15.957	8.529	85287.311
2	Lead Frame	Spot Ag Copper (C7025)	79.408	Copper	7440-50-8	97.150	75.573	40.392	403924.088
				Ni	7440-02-0	2.500	1.945	1.039	10394.341
				Si	7440-21-3	0.150	0.117	0.062	623.660
				Mg	7439-95-4	0.200	0.156	0.083	831.547
				Silver	7440-22-4		1.618	0.865	8647.921
3	Mold Compound	G700LX	86.394	Silica Fused	60676-86-0	81.500	70.411	37.633	376334.789
				Epoxy Resin	Trade Secret	10.000	8.639	4.618	46176.048
				Phenol Resin	Trade Secret	8.000	6.912	3.694	36940.838
				Carbon Black	1333-86-4	0.500	0.432	0.231	2308.802
4	Gold Wire	Gold (1.0 mils)	0.752	Au	7440-57-5	99.990	0.752	0.402	4018.904
				Dopant	-	0.010	0.000	0.000	0.402
5	Die Attach Material	CRM 1076 NS	1.686	Silver (Ag)	7440-22-4	82.000	1.383	0.739	7389.322
				Epoxy resin	9003-36-5	10.000	0.169	0.090	901.137
				Diluent	Trade Secret	2.000	0.034	0.018	180.227
				Dicyandiamide	461-58-5	0.900	0.015	0.008	81.102
				Hardener	Trade Secret	5.100	0.086	0.046	459.580
6	Solder	SN 100%	2.900	Sn	7440-31-5	99.987	2.900	1.550	15497.966
				Pb	7439-92-1	0.005	0.000	0.000	0.775
				Cu	7440-50-8	0.003	0.000	0.000	0.465
				Cd	7440-43-9	0.001	0.000	0.000	0.155
				Bi	7440-69-9	0.003	0.000	0.000	0.465
				Sb	7440-36-0	0.001	0.000	0.000	0.155
Total Unit Weight =			187.097						